

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A conductive bump for a semiconductor chip that has a pad-mounting surface which is provided with at least a bonding pad thereon, said conductive bump comprising:
a first metal layer adapted to be bonded to the bonding pad;
a conductive paste body formed on said first metal layer; and
a second metal layer formed on said paste body such that said paste body is sandwiched between said first and second metal layers.

2. (Original) The conductive bump of Claim 1, wherein said first metal layer has a base portion bonded to said bonding pad, and a peripheral portion extending from said base portion in a transverse direction relative to said base portion and cooperating with said base portion to confine a recess therebetween, said conductive paste body filling said recess, said recess being closed by said second metal layer.

3.-4. (Canceled)

5. (New) The conductive bump of claim 1, wherein said conductive paste comprises a thermosetting resin and a conductive filler.

6. (New) A conductive bump for a semiconductor chip that has a pad-mounting surface which is provided with at least a bonding pad thereon, said conductive bump comprising:
a first metal layer adapted to be bonded to the bonding pad;
a conductive paste body formed on said first metal layer, wherein said first metal layer is dimensioned to be at most slightly wider on the bonding pad in any direction than said paste body formed on said first metal layer; and
a second metal layer formed on said paste body such that said paste body is sandwiched between said first and second metal layers.